

ABSTRACT OF THE DISCLOSURE

[0031] A pressure piece for a compact power semiconductor module for direct mounting on a heat sink. The power semiconductor module has resilient connection leads for electrical connection to a printed circuit board disposed outside the housing. The pressure piece is dimensionally stable and effects pressure-contact between the printed circuit board and the connection leads. On its primary face facing the printed circuit board, the pressure piece has a plurality of pressure elements that space the primary face from the printed circuit board. In a preferred embodiment at least one rib includes a notch. Preferably, the pressure piece has at least one opening connecting its two primary faces permitting fluid flow between the edge of the pressure element and the notch.